

PRINTED WIRING BOARD AND METHOD OF MANUFACTURING A PRINTED WIRING
BOARD

CROSS REFERENCES TO RELATED APPLICATIONS

This application relates to and incorporates herein by reference
5 Japanese Patent Application 2001-338119 (filed on November 2,
2001).

BACKGROUND OF THE INVENTION

The present invention relates to printed wiring boards and
methods of manufacturing printing boards, and more particularly to
10 a printed wiring board that is a double-sided printed wiring board
or a multilayer printed wiring board with a plurality of
electrically-interconnected conductor pattern layers, and to the
manufacturing method thereof.

In Japanese Patent Application No.7-176846, conductor patterns
15 on a printed wiring board are interconnected electrically by
packing conductive paste, which contains metal particles and binder
resin, in a via hole formed in the printed wiring board and by
pressing the paste in the presence of heat. However, in that
publication, interconnection between the conductor patterns is
20 achieved by contact conduction between metal particles in the via
hole and by contact conduction between the metal particles and the
conductor patterns. Therefore, if the printed wiring board is used
in thermally harsh conditions, such as in a vehicle, the interlayer
connection resistance is likely to vary.

25 For example, in a high temperature environment, the reliability

of the interconnection is lowered by an increase in interlayer connection resistance because the contact resistances between metal particles and between the metal particles and the conductor patterns increase due to thermal expansion of the binder resin. The
5 problem becomes more critical as the density of the printed wiring board increases.

The present invention has been made accordingly to provide a more reliable printed wiring board.

BRIEF SUMMARY OF THE INVENTION

10 Basically, the invention is a printed wiring board formed by interconnected layers. Each layer includes an insulator film, in which a via hole is formed. A conductor pattern located on the insulator film, and the conductor pattern includes a conductor metal. A solid conductive material is located in the via hole. The
15 solid conductive material includes a first type of conductive material and a second type of conducting material. The first type of conducting material includes a metal, and the second type of conductive material includes an alloy formed by the metal and the conductor metal.

20 The invention is also a method of making a printed wiring board. The method includes packing via holes formed in an insulator material with an interlayer conducting material. The interlayer conducting material includes a first metal material and a second metal material, and the second metal material melts at a temperature
25 higher than a predetermined temperature. The method further includes stacking layers of the insulator film with conductor

patterns to form a stack such that the via holes are located between the conductor patterns in the stack. Further, the method includes forming a solid conductive material in each of the via holes to electrically connect the connector patterns by heating the stack to the predetermined temperature and pressing the stack. The solid conductive material of each via hole includes a unified conductive layer and a solid phase diffusion layer. The solid phase diffusion layer is formed by the first metal material and a conductor metal, and the conductor metal is a metal of the associated conductor pattern.

BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

Figure 1(a) is a diagrammatic cross sectional view showing a step in the manufacture of printed wiring boards according to the present invention;

Figure 1(b) is a view like Figure 1(a) showing a further step in the manufacture of the printed wiring boards;

Figure 1(c) is a view like Figure 1(a) showing a further step in the manufacture of the printed wiring boards;

Figure 1(d) is a view like Figure 1(a) showing a further step in the manufacture of the printed wiring boards;

Figure 1(e) is a view like Figure 1(a) showing a further step in the manufacture of the printed wiring boards;

Figure 2(a) is an enlarged diagrammatic cross sectional view showing a step in the manufacture of a printed wiring board according to a first embodiment of the present invention;

Figure 2(b) is a view like Figure 1(a) showing a further step

in the manufacture of the printed wiring board;

Figure 3 is a graph showing the results of an evaluation of adhesion between a copper foil and a conductive compound, where adhesion is represented by the vertical axis, and the quantities
5 of tin and silver in the compound are represented on the horizontal axis;

Figure 4 is a graph showing the change ratio in the via serial resistance of the printed wiring board of this invention, where resistance change ratio is represented by the vertical axis, and
10 the quantities of tin and silver in the compound is represented on the horizontal axis;

Figure 5 is a graph showing the results of an evaluation of adhesion between a copper foil and the conductive compound, where adhesion is represented by the vertical axis and the heating
15 temperature of the compound is represented on the horizontal axis;

Figure 6(a) is a view like Figure 2(a) showing a step in the manufacture of a printed wiring board according to a second embodiment;

Figure 6(b) is a view like Figure 2(b) showing a further step
20 in the manufacture of the printed wiring board of Figure 6(a);

Figure 7(a) is a view like Figure 1(a) showing a step in the manufacture of a printed wiring board according to a third embodiment;

Figure 7(b) is a view like Figure 2(b) showing a further step
25 in the manufacture of the printed wiring board of Figure 7(a);

Figure 8(a) is a view like Figure 1(a) showing a step in the manufacture of a printed wiring board according to a fourth

embodiment;

Figure 8(b) is a view like Figure 2(b) showing a further step in the manufacture of the printed wiring board of Figure 8(a);

Figure 9(a) is a view like Figure 1(a) showing a step in the
5 manufacture of a printed wiring board according to a further embodiment;

Figure 9(b) is a view like Figure 2(b) showing a further step in the manufacture of the printed wiring board of Figure 9(a);

Figure 10 is a diagrammatic cross sectional view showing a
10 stacking step in the manufacture of printed wiring boards according to a further embodiment of the present invention;

Figure 11 is a view like Figure 10 showing a stacking step in the manufacture of printed wiring boards according to a further embodiment of the present invention;

15 Figure 12 is a view like Figure 10 showing a stacking step in the manufacture of printed wiring boards according to a further embodiment of the present invention;

Figure 13 is a view like Figure 10 showing a stacking step in the manufacture of printed wiring boards according to a further
20 embodiment of the present invention; and

Figure 14 is a view like Figure 10 showing a stacking step in the manufacture of printed wiring boards according to a further embodiment of the present invention.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

25 (First embodiment)

In Fig. 1(a), a single-sided conductor pattern film 21 having

a conductor pattern 22 is defined by etching a conductive foil (a copper foil with 18 μm thickness in this embodiment) adhered to one side of a resin film 23. In this embodiment, a thermoplastic film, which is 25-75 μm thick and made of a mixture of 65-35%
5 polyetheretherketone resin and 35-65% polyetherimide resin, is used as the resin film 23.

After the formation of the conductor pattern 22 is completed as shown in Fig. 1(a), a substantially cylindrical via hole 24, for which the conductor pattern 22 serves as a bottom surface, is formed
10 by exposure to a carbon dioxide laser from the side of the resin film 23, as shown in Fig. 1(b). During the formation of the via hole, the conductor pattern is not perforated if the power and the exposure period of the carbon dioxide laser are set properly.

Other than the carbon dioxide laser, an excimer laser or the like
15 may be used for formation of the via hole 24. In addition to a laser, other ways of forming the via hole such as drilling may also be used. However, machining by laser beam is preferred because of its ability to machine a fine hole without damage to the conductor pattern 22.

After the formation of the via hole 24 is completed, as shown
20 in Fig. 1(b), conductive paste 50, which is a material for interlayer connection, is packed in the via hole 24 as shown in Fig. 1(c).

The paste is prepared by the steps described below. Terpeneol, an organic solvent, the quantity of which is 60g, is added to 300g
25 of tin particles. The tin particles are sometime referred to herein as first metal particles, and tin is sometimes referred to as a first metal. The mean particle size of the tin particles is 5 μm , and

the specific surface area of the tin particles is $0.5 \text{ m}^2/\text{g}$. Further, 300g of silver particles, which are sometimes referred to herein as second metal particles, are added. Silver is sometimes referred to herein as a second metal. The silver particles have a mean
5 particle size of $1 \mu\text{m}$ and a specific surface area of $1.2 \text{ m}^2/\text{g}$. The mixture is mixed to a paste by a mixer. The paste-like consistency of the material facilitates filling the via holes.

The conductive paste 50 is applied, or printed, and packed in the via hole 24 of the single-sided conductor pattern film 21 by
10 a screen printing machine with a metal mask, and the terpeneol is evaporated at 140-160 degrees (all temperatures herein are expressed in degrees Celsius) for 30 minutes. In this embodiment, the screen printing machine is used for packing the conductive paste 50 into the via hole 24. However, other methods such as applying
15 the paste with a dispenser or the like are may be used as long as the method reliably packs the paste.

Instead of terpeneol, other organic solvents may be used to make the paste. An organic solvent with a boiling point of 150-300 degrees is preferred. If organic solvents having boiling point of
20 150 degrees or lower are used, time-dependent variation of the viscosity of the conductive paste 50 increases. On the other hand, organic solvents having boiling points higher than 300 degrees have long evaporation times, and this slows production.

In this embodiment, the conductive paste 50 includes metal
25 particles, namely the tin particles and the silver particles. The metal particles preferably have a mean particle size of $0.1-20 \mu\text{m}$ and a specific surface area of $0.1-2.5 \text{ m}^2/\text{g}$.

If the metal particles have a mean particle size smaller than 0.1 μm or a specific surface area larger than $2.5\text{m}^2/\text{g}$, a lot of organic solvent is required to create a suitable viscosity for via hole packing. Conductive paste containing a lot of organic solvent
5 requires a relatively long time for evaporation, and relatively more gas is generated during the heating and interconnecting step if the evaporation is insufficient. Therefore, voids are likely to be generated in the via hole 24, which lower the reliability of the interconnection.

10 On the other hand, if the metal particles have a mean particle size larger than 20 μm or a specific surface area smaller than $0.1\text{m}^2/\text{g}$, packing the paste into the via hole 24 becomes difficult. In addition, the metal particles will tend to be unevenly distributed, which makes it difficult to create a homogeneous conductive alloy
15 compound 51 after heating. Thus, it is difficult to ensure the reliability of the interconnection.

Before the conductive paste 50 is packed into the via hole 24, the surface of the conductor pattern 22 facing the via hole 24 may be slightly etched or chemically reduced to improve solid phase
20 diffusion, which is described later.

When the conductive paste 50 has been packed into the via hole 24 and the evaporation of the terpeneol is completed, a plurality of single-sided conductor pattern films 21 (four films in this embodiment) are stacked as shown in Fig. 1(d). The two single-
25 sided conductor pattern films 21 of the lower side are stacked such that the side including the conductor pattern 22 faces downward. The two single-sided conductor pattern films 21 of the upper side

are stacked such that the side including the conductor pattern 22 faces upward.

The two inside single-sided conductor pattern films 21 are stacked together such that the sides having no conductor patterns 22 face each other. The two outer single-sided conductor pattern films 21 are stacked such that the sides including the conductor patterns 22 face outward as shown.

A top cover layer 36a, which is a resist film that covers the conductor pattern 22 of the top layer, is placed on the top of the stack of films 21 as shown. A bottom cover layer 36b, which is another resist film that covers the conductor pattern 22 of the bottom layer, is located at the bottom of the stack of films 21 as shown.

The top cover layer 36a is machined to provide a hole through which an electrode 32 is exposed in a predetermined position of the conductor pattern 22 on the top layer. The bottom cover layer 36b is machined to provide another hole through which an electrode 37 is exposed in a predetermined position of the conductor pattern 22 on the bottom layer. In this embodiment, the resin material described previously with respect to the resin film 23 is used for the cover layers 36a and 36b.

After stacking the single-sided conductor pattern films 21 and the cover layers 36a and 36b as shown in Fig. 1(d), the stacked unit is hot-pressed from the top and the bottom surfaces by a vacuum hot-press machine. In this embodiment, the stacked unit is pressed for 10-20 minutes under 2-10 MP pressure at a temperature of 240-350 degrees.

Thus, as shown in Fig. 1(e), the single-sided conductor pattern films 21 and the cover layers 36a, 36b are bonded together. While the resin films 23 and the cover layers 36a, 36b thermally fuse together into a unit, the conductor patterns 22 adjacent to the
5 conductive paste 50 in the via hole 24 are interconnected and a multilayer printed wiring board 100 with the electrodes 32 and 37 at the surfaces is provided. The resin film 23 and the cover layers 36a, 36b are made of the same thermoplastic resin so that they are unified by being thermally softened and pressed. In this
10 fabrication process, the process shown in Fig. 1(c) is a packing step and the processes shown in Figs. 1(d) and 1(e) are interconnecting steps.

Hereinafter, the interconnection is explained by referring to Fig. 2(a) and Fig. 2(b). Figure 2(a) and Figure 2(b) are partial,
15 enlarged views diagrammatically showing a representative one of the via holes 24. Before being heated by the vacuum hot-press machine, the paste 50 packed in the via hole 24 and subjected to evaporation is in the state shown in Fig. 2(a). In this state, both the first metal particles 61 (tin) and the second metal particles 62 (silver)
20 are mixed.

When the paste 50 is heated to 240-350 degrees, the tin particles melt and adhere to the surface of the silver particles, because the melting point of the tin particles 61 and that of the silver particles are 232 degrees and 961 degrees, respectively. As the
25 heating continues, fused tin begins diffusing from the surface of the silver particles, and an alloy (melting point, 480 degrees) is formed with tin and silver. With the tin-silver alloy formation,

as shown in Fig. 2(b), a conductive compound 51, which is a sintered alloy, is formed in the via hole 24 because the conductive paste 50 is under pressure of 2-10MP.

In addition, while the conductive compound 51 is formed in the via hole 24, the pressurized conductive compound 51 is pressed toward the surface forming the bottom of the via hole 24. Thus, the tin in the conductive compound 51 and copper in the copper foil forming the conductor pattern 22 diffuse mutually, and a solid phase diffusion layer 52 is formed at the interface between the conductive compound 51 and the conductor pattern 22.

Similarly, although not shown in Fig. 2(b), a solid phase diffusion layer is also formed by the tin in the conductive compound 51 and the copper in the copper foil of the conductor pattern 22 between the conductor pattern 22 and the conductive compound 51 in the via holes 24 in which the conductive patterns 22 form a bottom wall in the holes 24. Therefore, conductor patterns 22 at the top and bottom of the via hole 24 are electrically interconnected with the unified conductive compound 51 and the solid phase diffusion layer 52.

According to the configuration and the fabrication method described above, conductor patterns 22 of the printed wiring board 100 are electrically interconnected with both the unified conductive compound 51 made of tin-silver alloy sintered in the via hole 24 and the solid phase diffusion layer 52 made from tin and copper between the conductor pattern 22 and the conductive compound 51. Therefore, electrical interconnection between the conductor patterns 22 is not achieved by mere mechanical contact and there

is very little interlayer contact resistance. Therefore, the reliability of the interconnection is high.

In addition, stacked unification of the single-sided conductor pattern films 21 and the cover layer 36a, 36b and interconnection
5 of the conductor patterns 22 are performed simultaneously by the hot-press. Therefore, the number of fabrication steps for making the printed wiring board 100 is reduced along with the fabrication costs of the board.

In this embodiment, the metal components of the conductive paste
10 50 consist of 50weight% tin and 50weight% silver. The tin content in the metal components is preferably 20-80%.

Fig. 3 is a result of an evaluation conducted by the inventors of the adhesion between the copper foil forming the conductor patterns 22 and the conductive compound 51. Figure 3 shows the
15 variation in adhesion when the ratio of tin to silver in the conductive paste is varied.

To explain the evaluation procedures, first, the same tin particles and silver particles that were used for the conductive paste 50 described above were used as metal components. Terpeneol
20 was added to the metal components in an amount equivalent to 10weight% of the metal components, and the mixture is treated to create a paste. The paste is printed on the shiny side of a copper foil and the terpeneol is evaporated under the conditions described above. Subsequently, another copper foil is stacked on the paste
25 such that the matte side thereof contacts the paste. The two copper foils and the conductive compound between them are bonded by the hot-press under the conditions described above.

The reason that the shiny side of one copper foil and the matte side of the other copper foil face the paste is that a via hole packed with the conductive compound is formed between such sides when the single-sided conductor pattern films are stacked in the fabrication of the printed wiring board; that is, each film faces the same direction in the printed wiring board. The bonded two copper foils are peeled at the speed of 10 mm/min and the peeling strength is defined as the adhesion between the foils.

It turns out that a tin content between 20-80% provides a good level of adhesion (more than 1.0 N/mm). That is, a higher level of adhesion than that between the insulator and the copper foil is provided. The fracture mode in the peeling in of the material in the 20-80% tin content range is not boundary peeling between the copper foil and the conductive compound, but peeling due to internal fracturing of the conductive compound. Thus, a solid phase diffusion layer that is stronger than the conductive compound is formed between the copper foil and the conductive compound. Thus, the reliability of an interconnection that employs the solid phase diffusion layer is high.

Figure 4 is a result of an evaluation conducted by the inventors of the reliability of the interconnection and is a graph showing the variation in the resistance change ratio of the via serial resistance in the printed wiring board to the initial via serial resistance after a re-flow soldering process when the ratio of tin to silver in the conductive paste packed in the via hole is varied.

To explain the evaluation procedures, first, the same tin particles and silver particles that were used for the conductive

paste 50 described above were used as the metal components in this evaluation. Terpeneol was added to the metal components in an amount equivalent to 10weight% of the metal components, and the mixture was treated to create a paste. The paste was packed in the via hole of the single-sided conductor pattern film and the terpeneol was evaporated under the conditions described above. A copper foil was adhered to the insulator side of the single-sided conductor pattern film. The stacked unit is hot-pressed under the conditions described above. A double-sided board having conductor patterns for measuring via serial resistance is thus prepared.

Then, via serial resistance of the double-sided board was measured, and via serial resistance is again measured after the board is passed through a re-flow process at a temperature of 250 degrees for a period of 5 minutes. Then, the ratio of these values was calculated. This ratio is referred to as the resistance change ratio.

It turned out that a tin content between 20-80% ensures that the resistance change ratio is 20% or less, which is generally the maximum figure to provide good reliability.

It is possible to provide a printed wiring board with excellent connection reliability if the printed wiring board is manufactured by using, as an interlayer connecting material, the conductive paste 50 with 20-80% tin content, as described above.

In this embodiment, the temperature in the interlayer connecting process is 240-350 degrees. The heating temperature is preferably at least 220 degrees or more.

Figure 5 is the result of an evaluation conducted by the

inventors on the dependency of adhesion between the copper foil forming the conductor pattern and the conductive compound on heating temperature. Figure 5 shows the variation of the adhesion between the copper foil and the conductive compound when the heating
5 temperature is varied.

To explain the evaluation procedures, first, the conductor paste
50 is printed on the shiny side of a copper foil and the terpeneol was evaporated under conditions described above. Subsequently, another copper foil is stacked on the paste such that the matte side
10 thereof contacts the paste. The two copper foils and the conductive compound between them are bonded by pressing under the conditions described above at heating temperatures varied on a sample-by-sample basis.

The reason that the shiny side of one copper foil and the matte
15 side of the other copper foil face the paste is that a via hole packed with the conductive compound is formed between such sides when the single-sided conductor pattern films are stacked in the fabrication of the printed wiring board; that is, each film faces the same direction in the printed wiring board. The bonded two copper foils
20 are peeled at the speed of 10 mm/min and the peeling strength is defined as the adhesion between the foils.

The results show that a heating temperature higher than 220 degrees provides adhesion (the adhesion between the insulator and the copper foil) of more than 1.0N/mm, which is preferred. The
25 fracture mode in the peeling of the material in the 20-80% tin content range is not boundary peeling between the copper foil and the conductive compound, but peeling due to internal fracturing of

the conductive compound. This means that a solid phase diffusion layer that is stronger than the conductive compound is formed between the copper foil and the conductive compound.

As described above, a heating temperature higher than 220
5 degrees in the interlayer connecting process provides a good interlayer connection between the conductive compound and the solid phase diffusion layer.

In this embodiment, the pressure of the hot-pressing of the interlayer connecting material (50) is 2-10MPa. The pressing
10 pressure is preferably 0.5MPa or more. If the pressing pressure is lower than 0.5MPa, the metal particles are not sufficiently unified by sintering, and the solid phase diffusion layer is not sufficiently formed. The inventors have confirmed that a satisfactory interlayer connection is ensured by setting the
15 pressing pressure to 0.5MPa or more.

In the evaluation mentioned above, a copper foil, which has a matte side on which rust preventive film is formed, is used. Such a foil provides a good interlayer connection.

(Second embodiment)

20 Hereinafter, second embodiment of the present invention is explained with reference to the figures.

The second embodiment is different from the first embodiment in the composition of the conductive paste 50 and the process conditions after the packing process to improve the shape-retention
25 of the conductive paste 50. Therefore, the reference numerals used in the first embodiment are also used for the corresponding parts of this embodiment, and a detailed explanation thereof is omitted.

After the formation of the conductor pattern 22 and the via hole 24 is completed, as in the first embodiment, as shown in Figs. 1(a) and 1(b), conductive paste 50 for interlayer connection is packed in the via hole 24 of the single-sided conductor pattern film 21 as shown in Fig. 1(c).

The paste is prepared by the steps mentioned below. Terpineol, the quantity of which is 60g, is added to 300g of tin particles. The mean particle size of the tin particles is $5\mu\text{m}$, and the specific surface area of the tin particles is $0.5\text{ m}^2/\text{g}$. Further, 300g of silver particles are added. The silver particles have a mean particle size of $1\mu\text{m}$ and a specific surface area of $1.2\text{ m}^2/\text{g}$. In addition, indium particles (binder particles), the quantity of which is 6g, the mean particle size of which is $3\mu\text{m}$, and the specific surface area of which is $0.8\text{ m}^2/\text{g}$, are added. The mixture is treated by a mixer to make paste.

After packing the conductive paste 50, the terpineol is evaporated for 30 minutes at $140 - 160$ degrees. After the evaporation of the terpineol is completed, the single-sided conductor pattern film 21 is heated at $180 - 200$ degrees.

Before the heating, there are only indium particles 63 mixed with the tin particles 61 and the silver particles 62 in the via hole 24, as shown in Fig. 6(a). The indium particles 63 have a melting point of 160 degrees, thus the indium particles 63 are fused by the heat, and an indium portion 63a interconnects the tin particles 61 and the silver particles 62, as shown in Fig. 6(b). During the heating, part of the indium portion 63a diffuses into the tin particles 61 and the silver particles 62, and each particle is

firmly interconnected after cooling.

Consequently, the shape-retention of the conductor paste 50 is dramatically improved. Therefore, the conductor paste 50 resists dropping away in later processes.

5 The interconnection between the metal particles with the indium portion 63a is implemented by heating at 180 - 200 degrees in this embodiment. However, other temperature may be used as long as the temperature is lower than the melting point (232 degrees) of tin and the melting point (961 degrees) of silver (That is, lower than
10 the melting point of tin, since the melting point of tin is the lower of the two). The metal particles are interconnected without fusing the tin particles 61 and the silver particles 62. In addition, the metal particles may be interconnected via indium by hot pressing rather than merely heating. For example, it is possible to
15 interconnect the metal particles by letting a part of the indium diffuse into the tin particles 61 and the silver particles 62 by hot-pressing at 140 - 160 degrees between heating rollers or the like.

 In this embodiment, indium particles 63 are used as a binder.
20 However, other metal particles may be used as the binder as long as the particles have a lower melting point than those of tin and silver, and diffuse into the tin particle 61 and the silver particle 62.

 On completion of the packing of the conductor paste 50 in the
25 via hole 24 and the evaporation and heating, as shown in Figs. 1(d) and 1(e), a multilayer printed wiring board 100 is made by the same steps that are performed in the first embodiment. When the

conductive compound 51 is formed in the via hole 24, the indium is absorbed into the conductive compound 51 by diffusion.

According to the configuration and fabrication method described above, the same effects and advantages that result from the first
5 embodiment are produced. In addition, the interlayer connecting material 50, after being packing into the via hole 24, has better shape-retention and resists falling from the via hole (24). Therefore, the reliability of the interconnection is improved.

It is possible to add binder resin to the conductor paste 50 to
10 improve its shape-retention. However, excessive addition of binder resin is likely to increase the interlayer connecting resistance in the interlayer connecting process.

The materials and process conditions not explained in this embodiment are the same as those of the first embodiment.

15 (Third embodiment)

Hereinafter, a third embodiment of the present invention is explained by referring to the figures. The third embodiment differs from the first and second embodiments in the composition of the conductive paste 50 and in the process conditions that take place
20 after the packing process to improve the shape-retention of the conductive paste 50. The same reference numerals used in the first embodiment are used for corresponding parts of this embodiment, and a detailed explanation thereof is omitted.

After the formation of the conductor pattern 22 and the via hole
25 24 is completed, as in the first embodiment, as shown in Figs. 1(a) and (b), the conductive paste 50, which is for interlayer connection, is packed in the via hole 24 of the single-sided conductor pattern

film 21 as shown in Fig. 1(c).

Terpineol, the quantity of which is 60g, is added to 300g of tin particles. The mean particle size of the tin particles is $5\mu\text{m}$, and the specific surface area of the tin particles is $0.5\text{ m}^2/\text{g}$.
5 Further, 300g of relatively large silver particles are added. The relatively large silver particles have a mean particle size of $1\mu\text{m}$ and a specific surface area of $1.2\text{ m}^2/\text{g}$. Also, 0.6g of relatively small silver particles, which serve as binder particles and have a mean particle size of 5-7nm, are added. The mixture is mixed to
10 a paste by a mixer.

On completion of the packing of the conductive paste 50, the terpineol is evaporated for 30 minutes at 140-160 degrees. After the evaporation of the terpineol is completed, the single-sided conductor pattern film 21 is hot-pressed at 140-160 degrees between
15 heating rollers or the like.

Before the heating, the small silver particles 64, which have a mean particle size of 5-7nm, are mixed with the tin particles 61 and the relatively large silver particles 62, which have a mean particle size of $1\mu\text{m}$, in the via hole 24, as shown in Fig. 7(a).
20 The small silver particles 64 have such a large surface energy that parts of the small silver particles 64 diffuse into the tin particles 61 and the large silver particles 62 as a result of the heating, which interconnects the tin particles 61 and the large silver particles 62, as shown in the Fig. 7(b). When the conductive
25 compound 51 is formed in the via hole 24, the silver of the small silver particles 64 is absorbed into the conductive compound 51 by diffusion

Therefore, the shape-retention of the conductor paste 50 is dramatically improved, and the conductor paste 50 is prevented from dropping away in later processes.

The interconnection between the metal particles 61,62 and the small silver particles 64 is produced by hot-pressing at 140-160 degrees in this embodiment. However, other temperatures may be used as long as the heating temperature is lower than the melting point (232 degrees) of tin. The metal particles are interconnected without fusing the tin particles 61 and the large silver particles 62. In addition, by just heating, without hot-pressing, the metal particles may be interconnected via the small silver particles 64.

In this embodiment, the small silver particles 64 are used as binder particles. However, other metal particles may be used as long as the particles have a particle size of 1-100nm and diffuse into the tin particles 61 and the large silver particles 62. If the particle size is larger than 100nm, it is difficult to interconnect the particles at a lower temperature than the melting point of tin because the surface energy becomes lower. In addition, particles smaller than 1 nm are unfavorable due to the difficulty and high cost of fabricating such particles.

Upon completion of the packing of the conductor paste 50 in the via holes 24 and the improvement in the shape-retention through evaporation and heating, as shown in Figs. 1(d) and 1(e), the multilayer printed wiring board 100 is provided through the same processes used in the first embodiment.

According to the configuration and fabrication method described above, the same effects and advantages that result from the first

embodiment are provided. In addition, the interlayer connecting material 50, after being packing into the via hole 24, has an improved shape-retention and is prevented from dropping away from the via hole (24). Therefore, the interconnection is more reliable.

5 It is possible to add binder resin to the conductor paste 50 to improve its shape-retention. However, excessive addition of the binder resin will increase the interlayer connecting resistance in the interlayer connecting process. In this invention, binder resin is not needed and it is thus it is not necessary to increase the
10 interlayer connecting resistance.

(Fourth embodiment)

The fourth embodiment of the present invention is explained as follows by referring to the figures. The fourth embodiment is different from the first embodiment in the composition of the
15 conductive paste. Therefore, the same numerals used in the first embodiment are used for the corresponding parts of this embodiment, and a detailed explanation thereof is omitted.

After the formation of the conductor pattern 22 and the via hole 24 is completed according to the same steps used in the first
20 embodiment, as shown in Figs. 1(a) and (b), the conductive paste 50 is packed in the via holes 24 of the single-sided conductor pattern film 21, as shown in Fig. 1(c). Figure 1(c) shows the state where the conductor pattern 50 is packed. However, in this embodiment, a conductor paste 250, which serves as an interlayer
25 connecting material, is packed as shown in Fig. 8(a).

The paste 250 is prepared by the following steps. Terpeneol, the quantity of which is 60g, is added to 300g of relatively large

zinc particles. The mean particle size of the large zinc particles is $1\mu\text{m}$, and the specific surface area of the large zinc particles is $1.2\text{m}^2/\text{g}$. Further, 300g of relatively small zinc particles are added. The small zinc particles have a mean particle size of 5-10nm.

5 The mixture is made into a paste by a mixer.

On completion of the packing of the conductive paste 250, the terpeneol is evaporated for 30 minutes at 140-160 degrees. After the conductor paste 250 is packed in the via hole 24 and after the terpeneol is evaporated, as shown in Figs. 1(d) and 1(e), the
10 multilayer printed wiring board 100 is formed through the same steps employed in the first embodiment. Figure 1(e) shows the printed wiring board 100. The printed wiring board 200 of this embodiment, the layers of which are interconnected, is shown in Fig. 8(a).

The interconnection will now explained by referring to Figs.
15 8(a) and 8(b). Figures 8(a) and 8(b) are partial, enlarged views showing, diagrammatically, the via hole 24. Before being heated by the vacuum hot-press machine, the paste 250 packed in the via hole 24, after the evaporation, is in the state shown in Fig. 8(a). That is, both the large zinc particles 71 and the small zinc
20 particles 72 are mixed.

When the paste 250 is heated at 240-350 degrees, the small zinc particles 72 fuse and interconnect the large zinc particles 71. The small zinc particles 72 fuse due to their significantly large surface energy, and the large zinc particles 71, the melting point
25 of which is 419 degrees, do not fuse.

After the interconnection of the large zinc particles 71, as shown in Fig. 8(b), a conductive compound 251 made of unified zinc

is formed in the via hole 24, because the conductive paste 250 is under a pressure of 2-10MP.

In addition, while the conductive compound 251 is formed in the via holes 24, the pressurized conductive compound 251 is pressed toward the surfaces forming the bottoms of the via holes 24. Therefore, the zinc in the conductive compound 251 and the copper in the copper foil forming the conductor pattern 22 diffuse mutually, and a solid phase diffusion layer 252 is formed at the interface between the conductive compound 251 and the conductor pattern 22.

Although not shown in Fig. 8, a similar solid phase diffusion layer is formed between the zinc in the conductive compound 251 and the copper in the copper foil forming the conductor patterns 22 in the via holes that are oppositely oriented, that is, those that are closed by a conductor pattern 22 at the bottom side. Therefore, both the conductor patterns 22 at the top and the bottom of the via holes 24 are electrically interconnected with the unified conductive compound 251 and the solid phase diffusion layer 252.

According to the configuration and fabrication method described above, electrical interconnection between the conductor patterns 22 is not achieved by mechanical contact, thus the interlayer contact resistance hardly changes. Therefore, the reliability of the interconnection is improved. In addition, as in the first embodiment, unification of the single-sided conductor pattern films 21 and the cover layer 36a, 36b and interconnection of the conductor patterns 22 are performed simultaneously by the hot-press. Therefore, the number of fabrication steps for the printed wiring board 200 is reduced, which reduces the fabrication costs of the

boards.

In this embodiment, the small zinc particles 72 serve as fine metal particles. The preferred particle size thereof is 1-500nm. A particle size larger than 500 nm makes it difficult to
5 interconnect the zinc particles 71 at lower temperature than the melting point of zinc because surface energy is lower. In addition, particles having particle size smaller than 1 nm are difficult and expensive to produce. The particle size of the small zinc particles is more preferably 1-100nm.

10 In this embodiment, the heating temperature in the interlayer connecting process is 240-350 degrees. However, the heating temperature is preferably at least 220 degrees or more. The inventors have confirmed that the conductive compound 251 and the solid phase diffusion layer 252 are properly formed and good
15 interlayer connection is ensured at heating temperatures higher than 220 degrees.

In this embodiment, the pressing pressure in the interlayer connecting process is 2-10MPa. The pressing pressure is preferably 0.5MPa or more. If the pressing pressure is lower than 0.5MPa, the
20 zinc particles are not properly unified, and the solid phase diffusion layer is not properly formed. The inventors have confirmed that a satisfactory interlayer connection is ensured by setting the pressing pressure to 0.5MPa or more.

(Other embodiments)

25 In the first, second, and third embodiments described above, tin particles are used as the first metal particles. However, other metal particles may be used as long as the metal particles diffuse

mutually and form alloy with the metal (copper in each example mentioned above) making up the conductor pattern. Applicable metals are indium and the like. The first metal particles may be made of a single metal or a mixture of different metals.

5 In the first, second, and third embodiments described above, silver particles are used as the second metal particles. However, other metal particles may be used as long as the particles do not fuse during the interconnecting period and form an alloy with the first metal particles. Applicable metals are copper (melting point,
10 1083 degrees), gold (melting point, 1063 degrees), platinum (melting point, 1769 degrees), palladium (melting point, 1552 degrees), nickel (melting point, 1453 degrees), zinc (melting point, 419 degrees) or the like. The second metal particles may be made of a single metal or a combination of different metals.

15 In the first, second, and third embodiments described above, the conductive paste 50, which includes the first and the second metal particles, is applied. However, it is possible to use conductive paste that includes alloy particles, each of which is formed by an alloy of the first metal and the second metal. For example, as shown
20 in Fig. 9(a), conductive paste 150, which includes organic solvent and alloy particles 162, each of which includes 50weight% tin and 50weight% silver, is packed in the via holes 24 of the single-sided conductor pattern film 21 and subjected to evaporation. Afterward, the single-sided conductor pattern films 21 are preferably stacked
25 and the stacked unit is hot-pressed from both sides to form the unified conductive compound 51 by sintering the alloy particles in the via hole 24, as shown in Fig. 9(b).

The conductive compound 51 is pressurized while being pressed in the via hole 24 so that the compound 51 is pressed toward the surface of the conductor patterns 22 that form the bottoms of the via holes 24. Thus, the tin in the conductive compound 51 and the copper of the copper foil forming the conductor pattern 22 diffuse mutually in solid phase to form the solid phase diffusion layer 52 at the boundary between the conductive compound 51 and the conductor pattern 22. In this way the effects and advantages of the first embodiment result.

The first metal is not limited to tin. As described above, indium or the like may be used either separately or in combination. Moreover, the second metal is not limited to silver. As described above, copper, gold, platinum, palladium, nickel, zinc or the like are applicable either separately or in combination.

The metal components of the conductive paste 150 are 50weight% tin and 50weight% silver. As in the first, second, and third embodiments described above, the tin content of the metal components is preferably 20-80%.

In the fourth embodiment, the conductive paste 250 contains both the large zinc particles 71 and the small zinc particles 72. However, other metal particles are may be used as long as the particles diffuse mutually and form an alloy with the metal (copper in above-mentioned example) making up the conductor pattern. Applicable metals are aluminum, nickel and the like. These metals may be used separately or in combination as the large metal particle and the small, or fine, metal particle.

In addition, the conductive paste 250 may be the one that

contains only fine, or small, metal particles that diffuse and form an alloy with the metal making up the conductor pattern. That is, the paste 250 does not contain large metal particles. Many configurations are effective as long as it is possible to form the
5 conductive compound in the via hole by fusing the fine metal particles during the interlayer connecting process and to form a mutual solid phase diffusion layer between the formed conductive compound and the conductor pattern.

Namely, the metal making up the fine metal particles need not
10 diffuse mutually and form an alloy with the metal making up the conductor pattern as long as the large metal particles form an alloy with the fine metal particles and the large metal particles diffuse mutually with and form alloy with the metal making up the conductor pattern. Similarly, if the metal making up the fine metal particles
15 diffuses mutually with and forms an alloy with the metal making up the conductor pattern, the metal making up the large metal particles need not form alloy with the metal making up the conductor pattern as long as the large metal particles diffuse mutually with and form an alloy with the metal making up the fine metal particles.

20 In other words, if the two metals making up the large metal particles and the small metal particles mutually form an alloy, any metal combination works fine as long as at least one of the two metals making up either the large metal particles or the fine metal particles diffuses mutually with and forms an alloy with the metal
25 making up the conductor pattern. Therefore, for example, the following metal configurations are applicable. At least one metal of zinc, aluminum, and nickel is used for the large metal particles

and at least one metal of silver, copper, gold, platinum, and palladium is used for the fine metal particles. In addition, the opposite combinations are may be used.

In the first embodiment, there are only first metal particles
5 and second metal particles in the paste 50. In the second and third
embodiments, first metal particles, second metal particles and the
binder particles are included in the paste. However, other metal
particles that do not form an alloy with tin may be added to the
paste 50. For example, for adjusting the thermal expansion
10 coefficient of the conductive compound 51 to approximate that of
the insulator resin film 23, other metal particles, nonconductive
inorganic filler or the like may be added. However, excessive
amounts of such other materials may hinder the unification of the
conductive compound 51.

15 In the fourth embodiment, only the large metal particles and the
fine metal particles are included in the paste 250. However, other
metal particles that do not form an alloy with the metal particles
may be included. For example, for adjusting the thermal expansion
coefficient of the conductive compound 251 to approximate that of
20 the insulator resin film 23, other metal particles, nonconductive
inorganic filler or the like may be added. However, excessive
amounts of such other materials may hinder unification of the
conductive compound 251.

Furthermore, in each embodiment described above, the single-
25 sided conductor pattern films 21 are stacked, as shown in Fig. 1(d),
in the fabrication processes of the printed wiring board. However,
the stacking configuration is not limited to this one, but other

configurations are usable as long as the configurations are for a multilayer or double-sided printed wiring board requiring interlayer connection.

For example, a configuration shown in Fig. 10 is possible. In
5 Fig. 10, a multilayer printed wiring board is made by stacking a single-sided conductor pattern film 71 having a copper foil conductor pattern covering a whole side thereof, single-sided conductor pattern films 21, and a copper foil 81. Then, the stack is hot-pressed. Afterward, the copper foils are defined on both
10 sides. Another configuration, which is shown in Fig. 11, is also possible. In Figure 11, another multilayer printed wiring board is made by stacking single-sided conductor pattern films 21 and a double-sided film 91. Afterward the stacked unit is hot-pressed. Moreover, other configurations, such as that shown in Fig. 12 are
15 possible. In Figure 12, another multilayer printed wiring board is made by stacking the resin film 23 on both sides of the double-sided film 91. Then, the copper foils 81 are added to the stacked unit as shown. Afterward, the stacked body is hot-pressed.

Another configuration is shown in Figure 13. In Figure 13,
20 another multilayer printed wiring board is made by stacking the copper foils on the resin film 23, hot-pressing the stacked unit, and then defining the copper foils on both sides. In another configuration, which is shown in Fig. 14 another multilayer printed wiring board is made by stacking the single-sided conductor pattern
25 film 71, which has a copper foil conductor pattern covering a whole side thereof, with the copper foil 81. Then the stack is hot-pressed. Afterward, copper foils are defined on both sides.

In each embodiment, a resin film made of a mixture of 65-35% polyetheretherketone resin and 35-65% polyetherimide resin is used for the resin film 23 and the cover layers 36a and 36b. Instead of this film, it is possible to use a film made by adding
5 nonconductive filler to polyetheretherketone resin and polyetherimide resin. It is also possible to use separately polyetheretherketone (PEEK) or polyetherimide (PEI).

In addition, applicable materials for the resin film and the cover layer are polyethylene naphthalate (PEN), polyethylene
10 terephthalate (PET), polyether sulphone (PES), thermoplastic polyimide or, what is called liquid crystal polymer and the like. It is also possible to use a structure in which polyetherimide film is laminated by at least one of PEEK, PEI, PEN, PET, PES, thermoplastic polyimide and liquid crystal polymer. Other resin
15 films may be employed as long as the films are bonded together by hot-pressing and have the thermal resistance required in a later soldering process.

If a polyetherimide film laminated by a thermoplastic resin layer is applied, problems such as peeling and warping are
20 preventable because the 15-20 ppm thermal expansion coefficient of the polyimide is close to that (17 -20 ppm) of copper, which is the typical material used for wiring.

In the case of a double-sided printed wiring board, for example, thermosetting resin such as epoxy resin, bismaleimide triazine (BT),
25 polyphenylene ether (PPE), and polyimide (PI) in B stage are usable. Even in the case of a multilayer printed wiring board, thermosetting resin such as epoxy resin, BT, PPE, and PI in B stage are usable

for so-called build-up construction method.

In each embodiment described above, copper is used as the metal making up the conductor pattern 22. However, in the first, the second, the third embodiments, other than copper, it is possible to use metals that diffuse mutually in the solid phase with the first metal (tin in each example mentioned above) in the conductive compound 51. In addition, the conductor pattern 22 does not have to be entirely made of metal that diffuses mutually with the first metal in the conductive compound 51. It is possible to use a conductor pattern having a plated layer made of a metal such as silver and gold that diffuses mutually with tin (the first metal) contained in the conductive compound 51. Any conductor patterns are applicable as long as the patterns have metal that can diffuse mutually with the first metal contained in the conductive compound 51 at the position correspondent to the via hole 24.

In the fourth embodiment, other than copper, it is possible to use metals that diffuse mutually in the solid phase with the metal component (zinc in the example mentioned above) in the conductive compound 251. In addition, the conductor pattern 22 does not have to be entirely made of metal that diffuses mutually with the metal component contained in the conductive compound 251. It is possible to use a conductor pattern having a plated layer thereon made of a metal such as silver and gold that diffuses mutually with the metal component contained in the conductive compound 251. Any conductor patterns are applicable as long as the patterns have metal that can diffuse mutually with the metal component contained in the conductive compound 251 at the position corresponding to the via

hole 24.

In the first embodiment, the conductive paste 50 consists of two types of metal particles 61 and 62 and organic solvent. In the second embodiment, the conductive paste 50 consists of two types of metal particles 61, 62, and 63 and organic solvent. In the third embodiment, the conductive paste 50 consists of three types of metal particles 61, 62, and 64 and organic solvent. In the fourth embodiment, the conductive paste 250 consists of two types of metal particles 71 and 72 and organic solvent. A dispersing agent may be added to the conductive paste 50, 250 by an amount equivalent to 0.01-1.5 weight% of the solid components (e.g., the two types of metal particles 61 and 62 in the first embodiment) of the conductive paste 50, 250. This makes it easier to disperse homogeneously the metal particles in the conductive paste 50, 250. However, a dispersing agent content less than 0.01weight% scarcely provides a dispersion effect and a dispersing agent content more than 1.5weight% hinders the conductive compound from being unified by sintering. It is possible to use phosphoric ester and stearic ester or the like as a dispersing agent.

In each embodiment, the interlayer connecting material is the first type of conductive paste 50 or the second type of conductive paste 250. However, rather than a paste, granular material may be used as long as it is possible to pack the material in the via hole.

In each embodiment, the printed wiring boards 100, 200 consist of four layers. However, as a matter of course, as long as the board consists of a plurality of conductor pattern layers, the number thereof is not limited.

While preferred embodiments of the invention have been illustrated and described, these embodiments are capable of variation and modification and are not limited to the precise details set forth, and the invention includes variations and
5 modifications that fall within the scope of the appended claims.



What is claimed is:

1. A printed wiring board formed by interconnected layers, each layer comprising:
 - an insulator film, wherein at least one via hole is formed in the insulator film;
 - a conductor pattern located on the insulator film, wherein the conductor pattern includes a conductor metal; and
 - a solid conductive material, which includes metal components, located in the via hole, wherein the solid conductive material includes a first type of conductive material and a second type of conducting material, wherein the first type of conducting material includes a metal, and the second type of conductive material includes an alloy formed by the metal and the conductor metal.
2. The wiring board according to claim 1, wherein the metal is at least one of tin and indium.
3. The wiring board according to claim 1, wherein the metal is a first metal, and the first type of conducting material is an alloy of the first metal and a second metal, and the second metal is at least one of silver, copper, gold, platinum, palladium, nickel and zinc.
4. The wiring board according to claim 2, wherein the first type of conducting material is an alloy of the metal and at least one of silver, copper, gold, platinum, palladium, nickel and zinc.
5. The wiring board according to claim 1, wherein the metal accounts for 20-80wt% of the metal components of the solid conductive

material.



6. The wiring board according to claim 1, wherein the conductor metal is copper.

7. The wiring board according to claim 1, wherein the insulator film is made of thermoplastic resin or thermosetting resin.

8. The wiring board according to claim 1, wherein the first type of conductive material is a unified conductive compound and the second type of conductive material is a solid phase diffusion layer, wherein the solid phase diffusion layer is located between the unified conductive compound and the conductor pattern.

9. The wiring board according to claim 1, wherein the melting point of the metal is lower than a predetermined temperature to which the wiring board is heated to join the layers.

10. The wiring board according to claim 9, wherein the metal is a first metal, and the first type of conducting material is an alloy of the first metal and a second metal, and the melting point of the second metal is higher than the predetermined temperature.

11. A method of making a printed wiring board comprising:

packing via holes formed in an insulator material with an interlayer conducting material, wherein the interlayer conducting material includes a first metal material and a second metal material, and the second metal material melts at a temperature higher than a predetermined temperature;

stacking layers of the insulator film with conductor patterns to form a stack such that the via holes are located between the



conductor patterns in the stack;

forming a solid conductive material in each of the via holes to electrically connect the connector patterns by heating the stack to the predetermined temperature and pressing the stack, wherein the solid conductive material of each via hole includes a unified conductive layer and a solid phase diffusion layer, and the solid phase diffusion layer is formed by the first metal material and a conductor metal, wherein the conductor metal is a metal of the associated conductor pattern.

12. The method according to claim 11 including the step of employing at least one of tin and indium as the first metal material.

13. The method according to claim 11 including the step of employing at least one of silver, copper, gold, platinum, palladium, nickel and zinc as the second metal material.

14. The method according to claim 12, including the step of employing at least one of silver, copper, gold, platinum, palladium, nickel and zinc as the second metal material.

15. The method according to claim 11, including the step of employing the first metal material to account for 20-80wt% of the metal in the interlayer conductive material.

16. The method according to claim 11 including the step of employing copper as the conductor metal.

17. The method according to claim 11 including the step of employing thermoplastic resin or thermosetting resin as the material of the

insulation film.



18. The method according to claim 11 including employing particles made of the first metal material and particles made of the second metal material in the interlayer conductive material.
19. The method according to claim 11 including employing alloy particles that are made of the first metal material and the second metal material in the interlayer conductive material.
20. The method according to claim 11, wherein the heating heats the stack to a temperature of at least 220 degrees.
21. The method according to claim 11, wherein the pressing applies a pressure of at least 0.5MPa.
22. The method according to claim 11 including forming the interlayer connecting material as a paste prior to the packing, wherein the forming of the paste includes adding a solvent to particles made of the metal materials.
23. The method according to claim 22 including adding a dispersing agent to the paste, wherein the weight of the dispersing agent in the paste is 0.01 to 1.5% of the weight of all solids in the paste.
24. The method according to claim 22 further comprising:
 - adding binder particles to the paste; and
 - preheating the stack prior to the heating and pressing step and after the packing step to cause the binder particles to diffuse into the metal materials.



25. The method according to claim 24 further comprising the step of including a binder metal in the binder particles that melts at a temperature that is lower than that at which the first metal material melts, wherein the preheating heats the stack to a temperature that melts the binder metal, and the binder metal interconnects the first metal material and the second metal material as a result of the preheating.

26. The method according to claim 24 further comprising the step of employing binder particles that have a particle size of 1-100nm, wherein the first metal material and the second metal material are interconnected by a binder metal, which is included in the binder particles, as a result of the preheating.

27. The method according to claim 11 further comprising the step of including the first metal material and the second metal material in particles that form part of the paste, wherein the particles have a mean particle size of 0.1-20 μ m and a specific surface area of 0.1-2.5 m²/g.

28. A method of making a printed wiring board comprising:

packing via holes formed in an insulator material with an interlayer conducting material, wherein the interlayer conducting material includes particles that include metal material, wherein the particles have a mean particle size of 1-500nm;

stacking layers of the insulator film with conductor patterns to form a stack such that the via holes are located between the conductor patterns in the stack;



forming a solid conductive material in each of the via holes to electrically connect the connector patterns by heating the stack to the predetermined temperature and pressing the stack, wherein the solid conductive material of each via hole includes a unified conductive layer and a solid phase diffusion layer, and the solid phase diffusion layer is formed by the metal material and a conductor metal, wherein the conductor metal is a metal of the associated conductor pattern.

29. The method according to claim 28 including the step of employing at least one of zinc, aluminum, and nickel as the metal material.

30. The method according to claim 28, wherein the particles are relatively fine particles, and the method includes adding relatively large particles, which are relatively large compared to the relatively fine particles, to the interlayer connecting material, and the relatively large particles are made of the same material as the relatively fine particles.

31. The method according to claim 28, wherein the particles are relatively fine particles, and the method includes adding relatively large particles, which are relatively large compared to the relatively fine particles, to the interlayer connecting material, and the relatively large particles include metal that forms an alloy with the metal material of the relatively fine particles.

32. A method of making a printed wiring board comprising:
packing via holes formed in an insulator material with an



interlayer conducting material, wherein the interlayer conducting material includes relatively large particles that include metal material and relatively fine particles that include metal material, wherein the relatively fine particles have a mean particle size of 1-500nm, and wherein the metal material of the relatively large particles forms an alloy with the metal material of the relatively fine particles;

stacking layers of the insulator film with conductor patterns to form a stack such that the via holes are located between the conductor patterns in the stack;

forming a solid conductive material in each of the via holes to electrically connect the conductor patterns by heating the stack to the predetermined temperature and pressing the stack, wherein the solid conductive material of each via hole includes a unified conductive layer and a solid phase diffusion layer, and the solid phase diffusion layer is formed by one of the metal materials and a conductor metal of the associated conductor pattern.

33. The method according to claim 32 including the step of employing at least one of zinc, aluminum, and nickel as the metal material included in the relatively large particles.

34. The method according to claim 32 including the step of employing copper as the metal of the associated conductor pattern.

35. The wiring board according to claim 32 including the step of employing thermoplastic resin or thermosetting resin to form the insulating film.



36. The method according to claim 32, wherein the heating heats the stack to a temperature of at least 220 degrees.

37. The method according to claim 32, wherein the pressing applies a pressure of at least 0.5MPa.

38. The method according to claim 32 including forming the interlayer connecting material as a paste prior to the packing, wherein the forming of the paste includes adding a solvent to particles made of the metal materials.

39. The method according to claim 38 including adding a dispersing agent to the paste, wherein the weight of the dispersing agent added to the paste is 0.01 to 1.5% of the weight of all solids in the paste.